

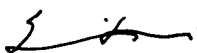
REMARKS

Further to the *Amendment* filed July 13, 2005 (received by OIPE July 15, 2005), the Applicants submit the present *Supplemental Amendment* to better recite the features of the present invention. Specifically, the Applicants have amended independent claims 1, 2, 4, 18, 20, 22, 24 and 26 to clearly and positively recite features of the method of manufacturing a semiconductor device that were previously recited in the preamble. Also, claims 1-4 and 18-27 have been amended to correct minor informalities. Specifically, "making the first conductive film into a desired shape with etching" has been changed to "etching the first conductive film" and "opening portion" has been changed to "opening." No new matter as been added.

The Applicants further note that Information Disclosure Statements were filed September 11, 2003, December 10, 2003 (received by OIPE December 12, 2003), and March 19, 2004 (received by OIPE March 22, 2004). A further Information Disclosure Statement is submitted herewith.

Examination on the merits is requested.

Respectfully submitted,



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